# NCP553, NCV553

# Voltage Regulator - CMOS, Low Iq, NOCAPE

## 80 mA

This series of fixed output NOCAP linear regulators are designed for handheld communication equipment and portable battery powered applications which require low quiescent. This series features an ultra−low quiescent current of 2.8 μA. Each device contains a voltage reference unit, an error amplifier, a PMOS power transistor, resistors for setting output voltage, current limit, and temperature limit protection circuits.

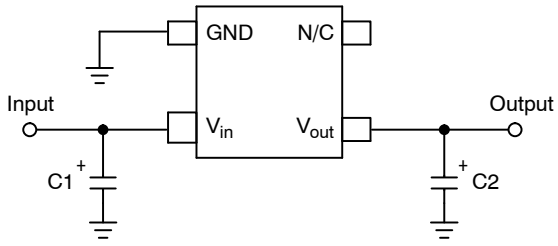
These voltage regulators have been designed to be used with low cost ceramic capacitors. The devices have the ability to operate without an output capacitor. The devices are housed in the micro−miniature SC82−AB surface mount package. Standard voltage versions are 1.5, 1.8, 2.5, 2.7, 2.8, 3.0, 3.3, and 5.0 V. Other voltages are available in 100 mV steps.

### Features

- Low Quiescent Current of 2.8 μA Typical
- Low Output Voltage Option
- Output Voltage Accuracy of 2.0%
- Industrial Temperature Range of −40°C to 85°C (NCV553, $T_A$ = −40°C to +125°C)
- These are Pb−Free Devices
- NCV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC−Q100 Qualified and PPAP Capable

### Typical Applications

- Battery Powered Consumer Products
- Hand−Held Instruments
- Camcorders and Cameras




This device contains 32 active transistors

**Figure 1. Typical Application Diagram**

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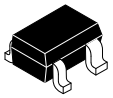
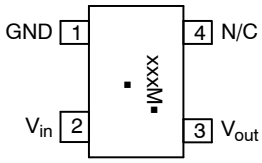


**SC82−AB (SC70−4)**
**SQ SUFFIX**
**CASE 419C**

### PIN CONNECTIONS & MARKING DIAGRAMS




(NCP553, NCV553 Top View)

xxx = Device Code
M = Date Code*
▪ = Pb−Free Package

(Note: Microdot may be in either location)

*Date Code orientation and/or position may vary depending upon manufacturing location.

### ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 7 of this data sheet.

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## PIN FUNCTION DESCRIPTION

| Pin | Pin Name | Description |
|---|---|---|
| 1 | GND | Power supply ground. |
| 2 | Vin | Positive power supply input voltage. |
| 3 | Vout | Regulated output voltage. |
| – | Enable | This input is used to place the device into low−power standby. When this input is pulled low, the device is disabled. If this function is not used, Enable should be connected to Vin. |
| 4 | N/C | No internal connection. |

## MAXIMUM RATINGS

| Rating | Symbol | Value | Unit |
|---|---|---|---|
| Input Voltage | $V_{in}$ | 12 | V |
| Output Voltage | $V_{out}$ | −0.3 to $V_{in}$ +0.3 | V |
| Power Dissipation and Thermal Characteristics<br>Power Dissipation<br>Thermal Resistance, Junction−to−Ambient | <br>$P_D$<br>$R_{\theta JA}$ | <br>Internally Limited<br>400 | <br>W<br>°C/W |
| Operating Junction Temperature | $T_J$ | +125 | °C |
| Operating Ambient Temperature<br>NCP553<br>NCV553 | $T_A$ | <br>−40 to +85<br>−40 to +125 | °C |
| Storage Temperature | $T_{stg}$ | −55 to +150 | °C |

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. This device series contains ESD protection and exceeds the following tests:
   Human Body Model 2000 V per MIL−STD−883, Method 3015
   Machine Model Method 200 V
2. Latch up capability (85°C) ±200 mA DC with trigger voltage.

## ELECTRICAL CHARACTERISTICS

($V_{in}$ = $V_{out(nom.)}$ + 1.0 V, $V_{enable}$ = $V_{in}$, $C_{in}$ = 1.0 μF, $C_{out}$ = 1.0 μF, $T_J$ = 25°C, unless otherwise noted.)

| Characteristic | Symbol | Min | Typ | Max | Unit |
|---|---|---|---|---|---|
| Output Voltage ($T_A$ = 25°C, $I_{out}$ = 10 mA)<br>1.5 V<br>1.8 V<br>2.5 V<br>2.7 V<br>2.8 V<br>3.0 V<br>3.3 V<br>5.0 V | $V_{out}$ | <br>1.455<br>1.746<br>2.425<br>2.646<br>2.744<br>2.94<br>3.234<br>4.900 | <br>1.5<br>1.8<br>2.5<br>2.7<br>2.8<br>3.0<br>3.3<br>5.0 | <br>1.545<br>1.854<br>2.575<br>2.754<br>2.856<br>3.06<br>3.366<br>5.100 | V |
| Output Voltage ($T_A$ = −40°C to 85°C, $I_{out}$ = 10 mA)<br>1.5 V<br>1.8 V<br>2.5 V<br>2.7 V<br>2.8 V<br>3.0 V<br>3.3 V<br>5.0 V | $V_{out}$ | <br>1.455<br>1.746<br>2.425<br>2.619<br>2.716<br>2.910<br>3.201<br>4.900 | <br>1.5<br>1.8<br>2.5<br>2.7<br>2.8<br>3.0<br>3.3<br>5.0 | <br>1.545<br>1.854<br>2.575<br>2.781<br>2.884<br>3.09<br>3.399<br>5.100 | V |
| Output Voltage ($T_A$ = −40°C, $I_{out}$ = 10 mA)<br>NCV553 −5.0 V | $V_{out}$ | 4.900 | 5.0 | 5.100 | V |
| Output Voltage ($T_A$ = +125°C, $I_{out}$ = 10 mA)<br>NCV553 −5.0 V | $V_{out}$ | 4.850 | 5.0 | 5.150 | V |
| Line Regulation ($V_{in}$ = $V_{out}$ + 1.0 V to 12 V, $I_{out}$ = 10 mA) | $Reg_{line}$ | – | 2.0 | 4.5 | mV/V |
| Load Regulation ($I_{out}$ = 1.0 mA to 80 mA, $V_{in}$ = $V_{out}$ + 2.0 V) | $Reg_{load}$ | – | 0.3 | 0.8 | mV/mA |
| Output Current ($V_{out}$ = ($V_{out}$ at $I_{out}$ = 80 mA) −3.0%)<br>1.5 V–3.9 V ($V_{in}$ = $V_{out(nom.)}$ + 2.0 V)<br>4.0 V–5.0 V ($V_{in}$ = 6.0 V) | $I_{o(nom.)}$ | <br>80<br>80 | <br>180<br>180 | <br>–<br>– | mA |
| Dropout Voltage ($T_A$ = −40°C to 125°C, $I_{out}$ = 80 mA, Measured at $V_{out}$ −3.0%)<br>1.5 V<br>1.8 V<br>2.5 V<br>2.7 V<br>2.8 V<br>3.0 V<br>3.3 V<br>5.0 V | $V_{in}$–$V_{out}$ | <br>–<br>–<br>–<br>–<br>–<br>–<br>–<br>– | <br>1300<br>1100<br>800<br>750<br>730<br>680<br>650<br>470 | <br>1800<br>1600<br>1400<br>1200<br>1200<br>1000<br>1000<br>800 | mV |
| Quiescent Current<br>(Enable Input = 0 V)<br>(Enable Input = $V_{in}$, $I_{out}$ = 1.0 mA to $I_{o(nom.)}$, $V_{in}$ = $V_{out}$ +2.0 V) | $I_Q$ | <br>–<br>– | <br>0.1<br>2.8 | <br>1.0<br>6.0 | μA |
| Output Short Circuit Current ($V_{out}$ = 0 V)<br>1.5 V–3.9 V ($V_{in}$ = $V_{out(nom.)}$ + 2.0 V)<br>4.0 V–5.0 V ($V_{in}$ = 6.0 V) | $I_{out(max)}$ | <br>100<br>100 | <br>300<br>300 | <br>450<br>450 | mA |
| Output Voltage Noise (f = 20 Hz to 100 kHz, $I_{out}$ = 10 mA)<br>($C_{out}$ = 1.0 μF) | $V_n$ | – | 90 | – | μVrms |
| Output Voltage Temperature Coefficient | $T_C$ | – | ±100 | – | ppm/°C |

3. Maximum package power dissipation limits must be observed.

$$PD = \frac{T_{J(max)} - T_A}{R_{\theta JA}}$$

4. Low duty cycle pulse techniques are used during testing to maintain the junction temperature as close to ambient as possible.

## DEFINITIONS

### Load Regulation

The change in output voltage for a change in output current at a constant temperature.

### Dropout Voltage

The input/output differential at which the regulator output no longer maintains regulation against further reductions in input voltage. Measured when the output drops 3.0% below its nominal. The junction temperature, load current, and minimum input supply requirements affect the dropout level.

### Maximum Power Dissipation

The maximum total dissipation for which the regulator will operate within its specifications.

### Quiescent Current

The quiescent current is the current which flows through the ground when the LDO operates without a load on its output: internal IC operation, bias, etc. When the LDO becomes loaded, this term is called the Ground current. It is actually the difference between the input current (measured through the LDO input pin) and the output current.

### Line Regulation

The change in output voltage for a change in input voltage. The measurement is made under conditions of low dissipation or by using pulse technique such that the average chip temperature is not significantly affected.

### Line Transient Response

Typical over and undershoot response when input voltage is excited with a given slope.

### Thermal Protection

Internal thermal shutdown circuitry is provided to protect the integrated circuit in the event that the maximum junction temperature is exceeded. When activated at typically 160°C, the regulator turns off. This feature is provided to prevent failures from accidental overheating.

### Maximum Package Power Dissipation

The maximum power package dissipation is the power dissipation level at which the junction temperature reaches its maximum operating value, i.e. 125°C. Depending on the ambient power dissipation and thus the maximum available output current.

## TYPICAL CHARACTERISTICS

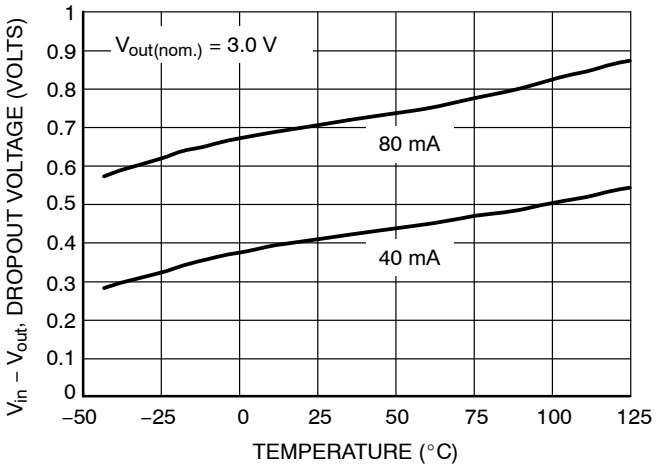


**Figure 2. Dropout Voltage versus Temperature**

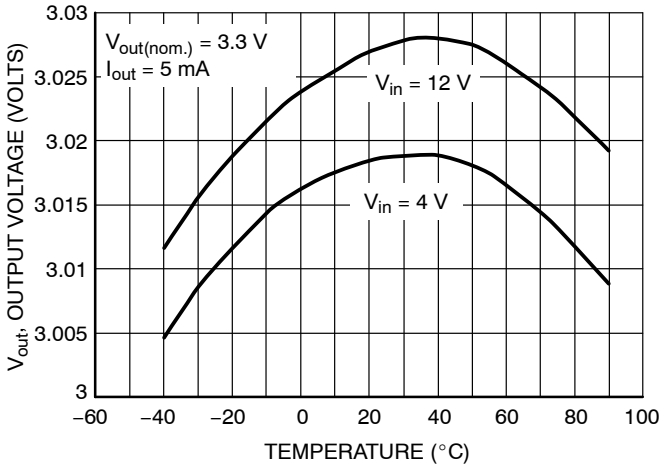


**Figure 3. Output Voltage versus Temperature**

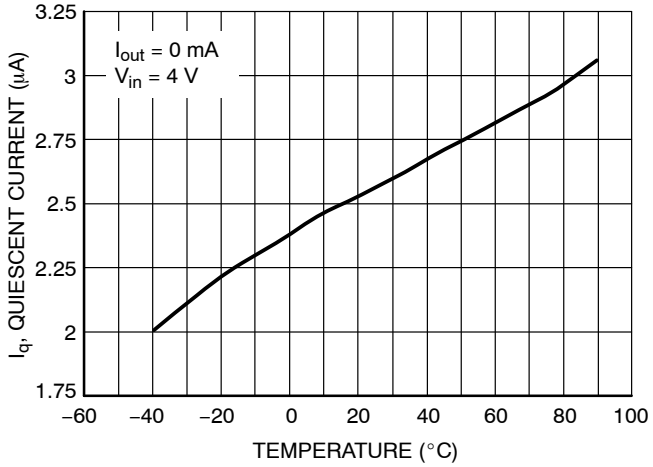


**Figure 4. Quiescent Current versus Temperature**

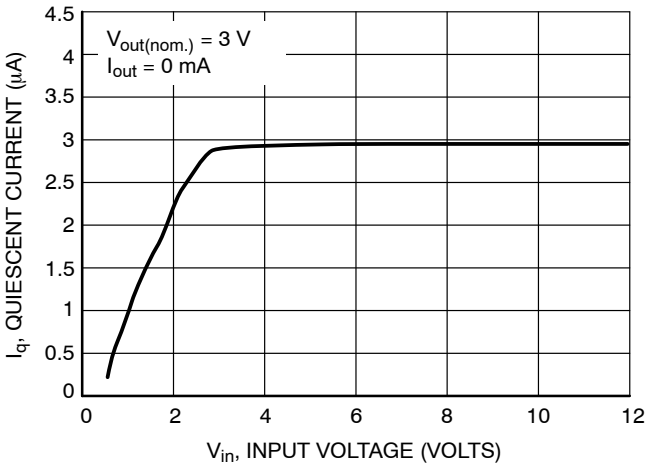


**Figure 5. Quiescent Current versus Input Voltage**

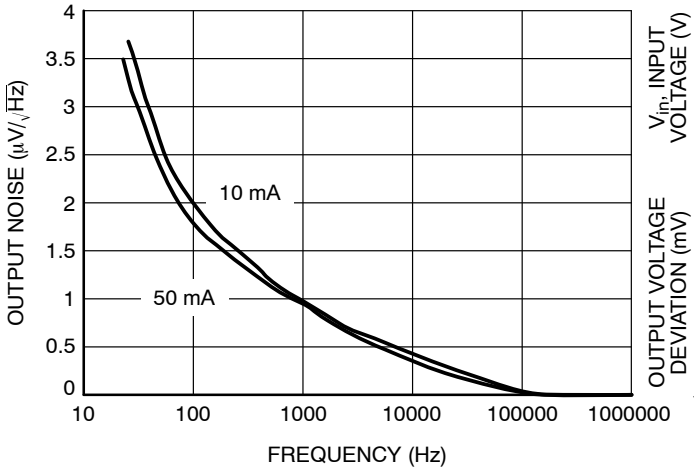


**Figure 6. Output Noise Density**

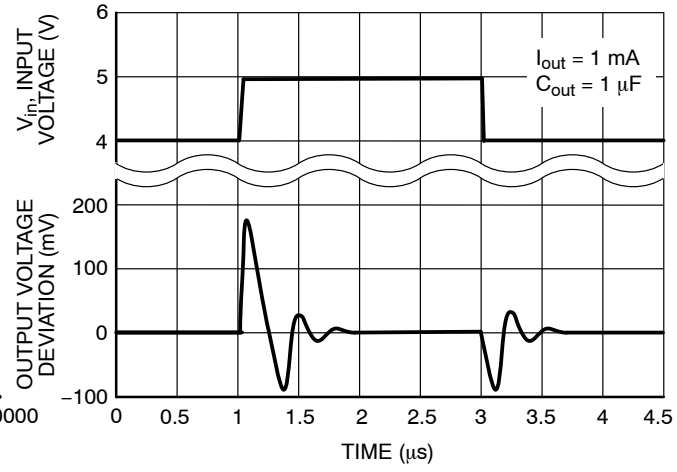


**Figure 7. Line Transient Response**

## TYPICAL CHARACTERISTICS

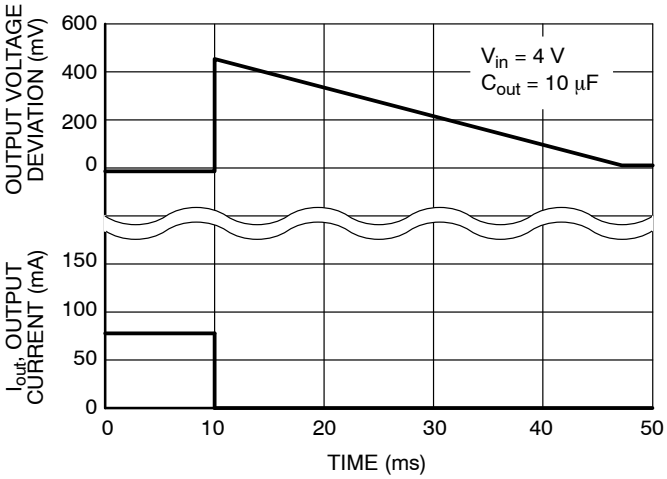


**Figure 8. Load Transient Response**

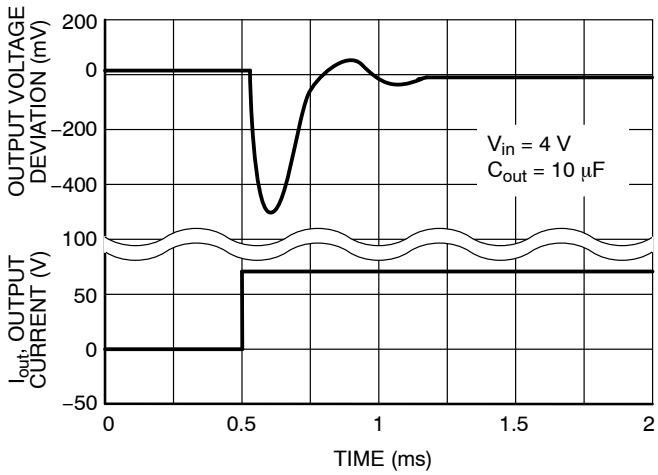


**Figure 9. Load Transient Response**

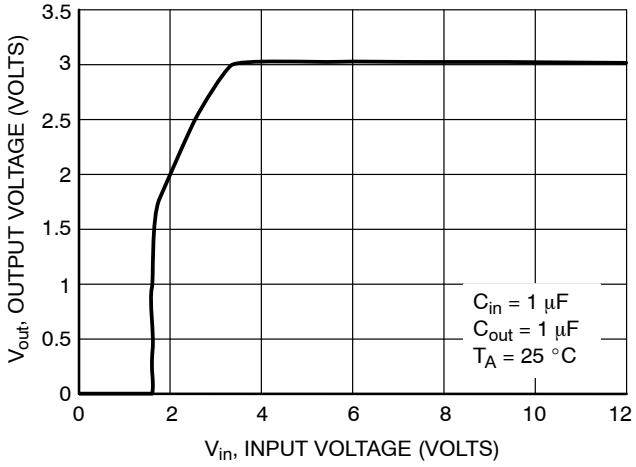


**Figure 10. Output Voltage versus Input Voltage**

## APPLICATIONS INFORMATION

A typical application circuit for the NCP553 series is shown in Figure 1, front page.

### Input Decoupling (C1)

A 1.0 μF capacitor either ceramic or tantalum is recommended and should be connected close to the package. Higher values and lower ESR will improve the overall line transient response. If large line or load transients are not expected, then it is possible to operate the regulator without the use of a capacitor.
TDK capacitor: C2012X5R1C105K, or C1608X5R1A105K

### Output Decoupling (C2)

The NCP553 are very stable regulators and do not require any specific Equivalent Series Resistance (ESR) or a minimum output current. If load transients are not to be expected, then it is possible for the regulator to operate with no output capacitor. Otherwise, capacitors exhibiting ESRs ranging from a few mΩ up to 10 Ω can thus safely be used. The minimum decoupling value is 0.1 μF and can be augmented to fulfill stringent load transient requirements. The regulator accepts ceramic chip capacitors as well as tantalum devices. Larger values improve noise rejection and load regulation transient response.
TDK capacitor: C2012X5R1C105K, C1608X5R1A105K, or C3216X7R1C105K

### Hints

Please be sure the Vin and GND lines are sufficiently wide. When the impedance of these lines is high, there is a chance to pick up noise or cause the regulator to malfunction.

Set external components, especially the output capacitor, as close as possible to the circuit, and make leads as short as possible.

### Thermal

As power across the NCP553 increases, it might become necessary to provide some thermal relief. The maximum power dissipation supported by the device is dependent upon board design and layout. Mounting pad configuration on the PCB, the board material and also the ambient temperature effect the rate of temperature rise for the part. This is stating that when the devices have good thermal conductivity through the PCB, the junction temperature will be relatively low with high power dissipation applications.

The maximum dissipation the package can handle is given by:

$$PD = \frac{T_{J(max)} - T_A}{R_{\theta JA}}$$

If junction temperature is not allowed above the maximum 125°C, then the NCP553 can dissipate up to 250 mW @ 25°C.

The power dissipated by the NCP553 can be calculated from the following equation:

$$P_{tot} = [V_{in} * I_{gnd}(I_{out})] + [V_{in} - V_{out}] * I_{out}$$

or

$$V_{inMAX} = \frac{P_{tot} + V_{out} * I_{out}}{I_{gnd} + I_{out}}$$

If an 80 mA output current is needed then the ground current from the data sheet is 2.8 μA. For an NCP553 (3.0 V), the maximum input voltage will then be 6.12 V.

### ORDERING INFORMATION

| Device | Nominal Output Voltage (Note 5) | Marking | Package | Shipping† |
|---|---|---|---|---|
| NCP553SQ15T1G | 1.5 | LBE | SC82−AB (SC70−4) (Pb−Free) | 3000 Units/ 8″ Tape & Reel |
| NCP553SQ18T1G | 1.8 | LBF | | |
| NCP553SQ25T1G | 2.5 | LBG | | |
| NCP553SQ27T1G | 2.7 | LBH | | |
| NCP553SQ28T1G | 2.8 | LBI | | |
| NCP553SQ30T1G | 3.0 | LBJ | | |
| NCP553SQ33T1G | 3.3 | LBK | | |
| NCP553SQ50T1G | 5.0 | LBL | | |
| NCV553SQ15T1G* | 1.5 | AAF | | |
| NCV553SQ30T1G* | 3.0 | LBJ | | |
| NCV553SQ50T1G* | 5.0 | LFT | | |

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.
*NCV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC−Q100 Qualified and PPAP Capable
5. Additional voltages in 100 mV steps are available upon request by contacting your ON Semiconductor representative.

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# MECHANICAL CASE OUTLINE
## PACKAGE DIMENSIONS

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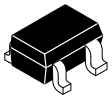
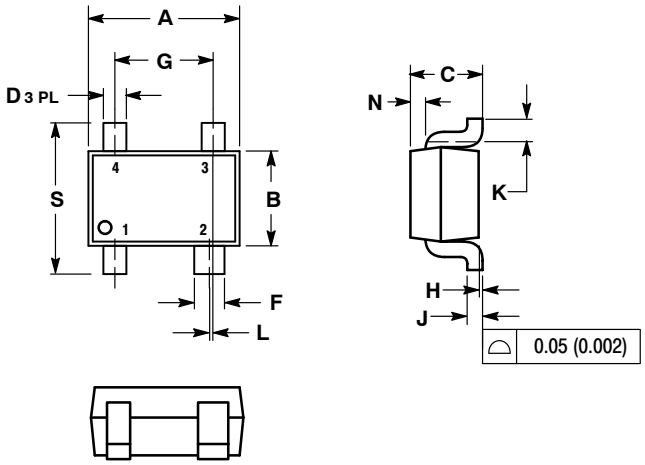


**SC−82AB**
CASE 419C−02
ISSUE F

DATE 22 JUN 2012

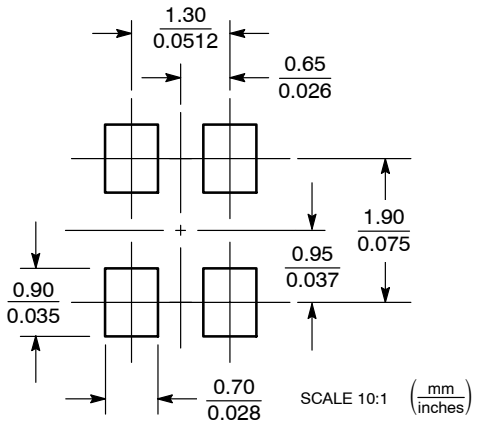
**SCALE 4:1**




NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. 419C−01 OBSOLETE. NEW STANDARD IS 419C−02.
4. DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

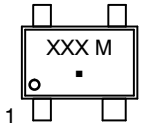
| | MILLIMETERS | | INCHES | |
|---|---|---|---|---|
| DIM | MIN | MAX | MIN | MAX |
| A | 1.80 | 2.20 | 0.071 | 0.087 |
| B | 1.15 | 1.35 | 0.045 | 0.053 |
| C | 0.80 | 1.10 | 0.031 | 0.043 |
| D | 0.20 | 0.40 | 0.008 | 0.016 |
| F | 0.30 | 0.50 | 0.012 | 0.020 |
| G | 1.10 | 1.50 | 0.043 | 0.059 |
| H | 0.00 | 0.10 | 0.000 | 0.004 |
| J | 0.10 | 0.26 | 0.004 | 0.010 |
| K | 0.10 | −−− | 0.004 | −−− |
| L | 0.05 BSC | | 0.002 BSC | |
| N | 0.20 REF | | 0.008 REF | |
| S | 1.80 | 2.40 | 0.07 | 0.09 |

### SOLDERING FOOTPRINT*




*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

### GENERIC MARKING DIAGRAM*




XXX = Specific Device Code
M = Month Code
▪ = Pb−Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, “G” or microdot “ ▪”, may or may not be present.

| | | | |
|---|---|---|---|
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| **DESCRIPTION:** | **SC−82AB** | | **PAGE 1 OF 1** |

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